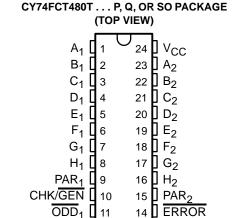
- **Function, Pinout, and Drive Compatible** With FCT and F Logic
- Reduced V<sub>OH</sub> (Typically = 3.3 V) Versions of Equivalent FCT Functions
- **Edge-Rate Control Circuitry for** Significantly Improved Noise Characteristics
- Ioff Supports Partial-Power-Down Mode Operation
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- Two 8-Bit Parity Generators/Checkers
- **Open-Drain Active-Low Parity-Error Output**
- **Expandable for Larger Word Widths**
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- CY54FCT480T
  - 32-mA Output Sink Current
  - 12-mA Output Source Current
- CY74FCT480T
  - 64-mA Output Sink Current
  - 32-mA Output Source Current

#### description

The 'FCT480T devices are high-speed, dual, 8-bit parity generators/checkers. Each parity generator/checker accepts eight data bits and one parity bit as inputs, and generates a sum and parity-error (ERROR) output. These devices can be used in odd-parity systems. ERROR is an open-drain output designed for easy expansion of

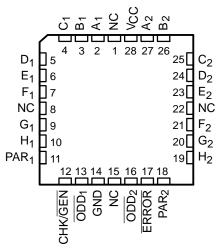


CY54FCT480T...L PACKAGE (TOP VIEW)

12

GND

13 ODD<sub>2</sub>



NC - No internal connection

the word width by a wired-OR connection of several 'FCT480T devices. Because no additional logic is needed, the parity-generation or parity-checking times remain the same as for an individual 'FCT480T device.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



testing of all parameters.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **ORDERING INFORMATION**

TA	PACKAGET		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DIP – P	Tube	6.1	CY74FCT480BTPC	CY74FCT480BTPC
	QSOP - Q	Tape and reel	6.1	CY74FCT480BTQCT	FCT480B
-40°C to 85°C	SOIC - SO	Tube	6.1	CY74FCT480BTSOC	FCT480B
-40°C to 85°C	3010 - 30	Tape and reel	6.1	CY74FCT480BTSOCT	FC1460B
	DIP – P	Tube	7.5	CY74FCT480ATPC	CY74FCT480ATPC
	QSOP - Q	Tape and reel	7.5	CY74FCT480ATQCT	FCT480A
–55°C to 125°C	LCC – L	Tube	7	CY54FCT480BTLMB	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

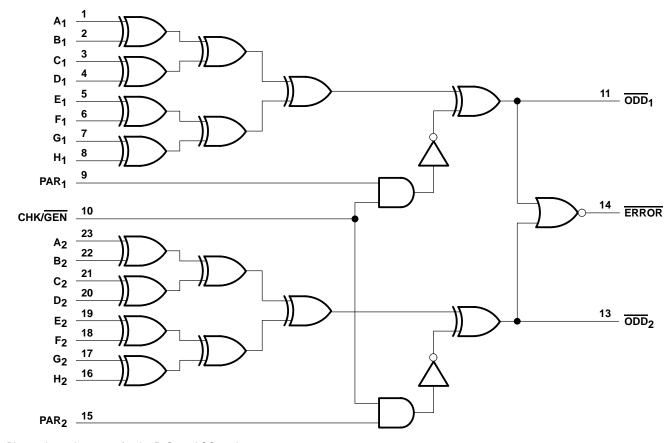
#### **FUNCTION TABLE**

	INPUT	'S				OUTPUT	S
A <sub>1</sub> -H <sub>1</sub>	A <sub>2</sub> -H <sub>2</sub>	CHK/GEN	PAR <sub>1</sub>	PAR <sub>2</sub>	ODD <sub>1</sub>	ODD <sub>2</sub>	ERROR
		Н	Н	Н	L	L	Н
	Number of	Н	L	Н	Н	L	L
	A <sub>2</sub> -H <sub>2</sub> inputs,	Н	Н	L	L	Н	L
	high is even	Н	L	L	Н	Н	L
Number of		L	X	Χ	Н	Н	L
A <sub>1</sub> -H <sub>1</sub> inputs, high is even	Number of	Н	Н	Н	L	Н	L
		Н	L	Н	Н	Н	L
	inputs A <sub>2</sub> –H <sub>2</sub> ,	н	Н	L	L	L	Н
	high is odd	н	L	L	Н	L	L
		L	Χ	Χ	Н	L	L
		Н	Н	Н	Н	L	L
	Number of	Н	L	Н	L	L	Н
	A <sub>2</sub> –H <sub>2</sub> inputs,	Н	Н	L	Н	Н	L
	high is even	Н	L	L	L	Н	L
Number of		L	X	Χ	L	Н	L
A <sub>1</sub> -H <sub>1</sub> inputs, high is odd		Н	Н	Н	Н	Н	L
g 0 0 0 0	Number of	Н	L	Н	L	Н	L
	A <sub>2</sub> -H <sub>2</sub> inputs,	Н	Н	L	Н	L	L
	high is odd	Н	L	L	L	L	Н
		L	Χ	Χ	L	L	Н

H = High logic level, L = Low logic level, X = Don't care



## logic diagram



Pin numbers shown are for the P, Q, and SO packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range to ground potential	
DC output voltage range	
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 1): P package	67°C/W
(see Note 2): Q package	61°C/W
(see Note 2): SO package	46°C/W
Ambient temperature range with power applied, T <sub>A</sub>	–65°C to 135°C
Storage temperature range, T <sub>stq</sub>	−65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



## **CY54FCT480T, CY74FCT480T DUAL 8-BIT PÁRITY GENERATORS/CHECKERS**

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## recommended operating conditions (see Note 3)

		CY54FCT480T			CY	0T	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
loh	High-level output current			-12			-32	mA
l <sub>OL</sub>	Low-level output current			32			64	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST SOMPLEIONS	C	/54FCT48	30T	CY	74FCT48	0T	LINIT
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$		-0.7	-1.2				V
VIK	V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = -18 mA					-0.7	-1.2	
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$	2.4	3.3					
Voн	V <sub>CC</sub> = 4.75 V				2.4	3.3		V
	$I_{OH} = -32 \text{ mA}$				2			
\/a.	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$		0.3	0.55				V
VOL	$V_{CC} = 4.75 \text{ V}, \qquad I_{OL} = 64 \text{ mA}$					0.3	0.55	V
$V_{hys}$	All inputs		0.2			0.2		V
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$			5				
IJ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = V_{CC}$						5	μΑ
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			±1				
lіН	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						±1	μΑ
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$			±1				μА
I⊫	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						±1	μΑ
l <sub>off</sub>	$V_{CC} = 0 \text{ V}, \qquad V_{OUT} = 4.5 \text{ V}$			±1			±1	μΑ
la a †	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$	-60	-120	-225				mA
los <sup>‡</sup>	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$				-60	-120	-225	IIIA
lo=u	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 2.7 \text{ V}$			10				
lozh	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 2.7 \text{ V}$						10	μΑ
la	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0.5 \text{ V}$			-10				
lozl	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0.5 \text{ V}$						-10	μΑ
laa	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				A
Icc	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.2 \text{ V}$	_				0.1	0.2	mA
Alaa	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}$ , $f_1 = 0$ , Outputs open		0.5	2				m A
∆ICC	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 3.4 V§, f <sub>1</sub> = 0, Outputs open					0.5	2	mA

<sup>&</sup>lt;sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>‡</sup> Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		TEST CONDITION	CY	54FCT48	0T	CY	74FCT48	0T	LINUT	
PARAMETER		TEST CONDITION	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
ICCD¶	$V_{CC} = 5.5 \text{ V}$ , Outpose one bit switching a $V_{IN} \le 0.2 \text{ V}$ or $V_{IN}$	at 50% duty cycle,		0.06	0.12				mA/	
ICCD"	$V_{CC} = 5.25 \text{ V}, \text{ Out}$ One bit switching a $V_{IN} \le 0.2 \text{ V}$ or $V_{IN}$	at 50% duty cycle,						0.06	0.12	MHz
		One bit switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	$V_{CC} = 5.5 \text{ V},$ $f_0 = 0 \text{ MHz},$	at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		1	2.4				
	Outputs open	16 bits switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		2.5	5				
IC#		at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		6.5	21				mA
10"		One bit switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	$V_{CC} = 5.25 \text{ V},$ $f_0 = 0 \text{ MHz},$	at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND					1	2.4	
	Outputs open	16 bits switching at f <sub>1</sub> = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					2.5	5	
		at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND					6.5	21	
C <sub>i</sub>					5	10		5	10	pF
Co					9	12		9	12	pF

<sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

Where:

I<sub>C</sub>= Total supply current

ICC= Power-supply current with CMOS input levels

 $\Delta I_{CC}$ = Power-supply current for a TTL high input ( $V_{IN} = 3.4 \text{ V}$ )

DH= Duty cycle for TTL inputs high

N<sub>T</sub>= Number of TTL inputs at D<sub>H</sub>

I<sub>CCD</sub>= Dynamic current caused by an input transition pair (HLH or LHL)

 $f_0$ = Clock frequency for registered devices, otherwise zero

f<sub>1</sub>= Input signal frequency

 $N_1$ = Number of inputs changing at  $f_1$ 

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I<sub>CC</sub> formula.



This parameter is derived for use in total power-supply calculations.

 $<sup>^{\#}</sup>$ IC=ICC +  $\triangle$ ICC  $\times$  DH  $\times$  NT + ICCD (f<sub>0</sub>/2 + f<sub>1</sub>  $\times$  N<sub>1</sub>)

## CY54FCT480T, CY74FCT480T DUAL 8-BIT PARITY GENERATORS/CHECKERS

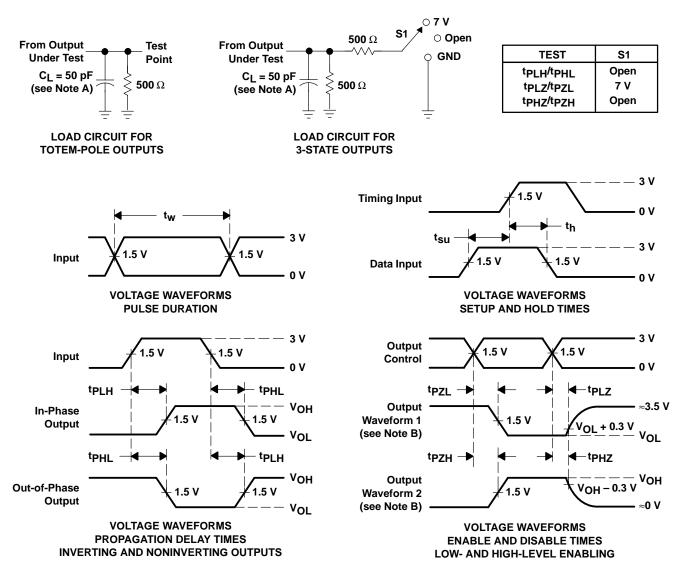
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## switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT	480AT	CY54FCT	480BT	CY74FC1	480BT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>	А	ODD		7.5		7		6.1	ns
t <sub>PHL</sub>	Α	(see Figure 1)		7		6.6		6.1	115
t <sub>PLH</sub>	CHK/ <del>GEN</del>	ODD		6.5		6.3		5.9	ns
t <sub>PHL</sub>	CHNGEN	(see Figure 1)		7.5		7.4		5.9	115
t <sub>PLH</sub> †	А	ERROR		7		7		6.1	no
t <sub>PHL</sub>	A	(see Figure 2)		8.5		8.1		6.5	ns
<sup>t</sup> PLH	CHK/ <del>GEN</del>	ERROR		7.5		7.1		5.7	ns
tpHL	CHNGEN	(see Figure 2)		7		6.9		5.5	115

 $<sup>^{\</sup>dagger}$  tpLH is measured up to VOUT = VOL + 0.3 V.

#### PARAMETER MEASUREMENT INFORMATION

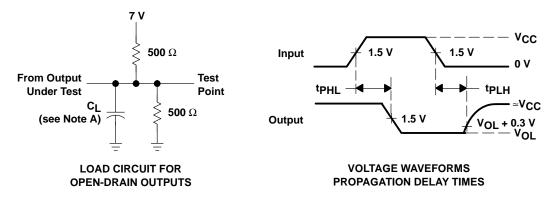


NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION FOR OPEN-DRAIN OUTPUTS



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns.  $t_f \leq 3$  ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

#### PACKAGE OPTION ADDENDUM





#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
CY54FCT480BTLMB	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
CY74FCT480ATPC	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480ATPCE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480ATQCT	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480ATQCTE4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480ATQCTG4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTPC	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480BTPCE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT480BTQCT	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT480BTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT480BTSOCTG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



## PACKAGE OPTION ADDENDUM

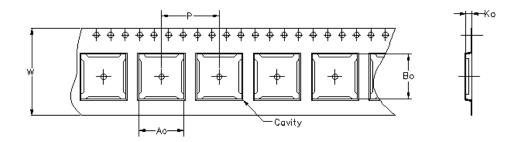
21-May-2007

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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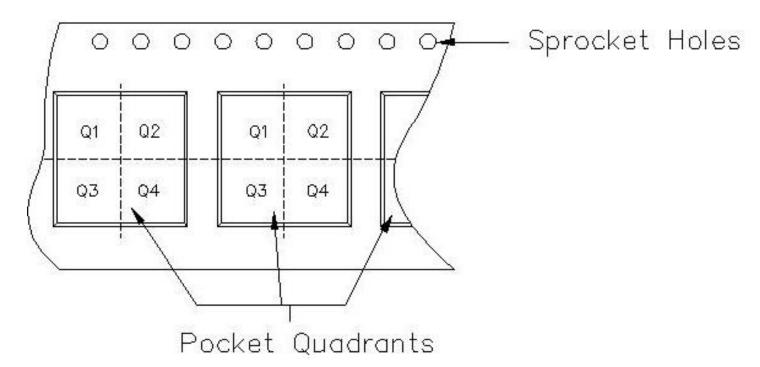
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Carrier tape design is defined largely by the component lentgh, width, and thickness.

Ao =	Dimension	designed	to	accommodate	the	component	width.
Bo =	Dímension	designed	to	accommodate	the	component	length.
Ko =	Dímension	designed	to	accommodate	the	component	thickness.
W =	Overall widt	h of the	car	rier tape.			
P =	Pitch betwe	en succes	ssiv	e cavity center	·s.		



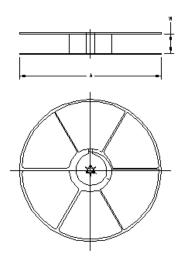
## TAPE AND REEL INFORMATION



## **PACKAGE MATERIALS INFORMATION**

19-May-2007

	Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74	FCT480ATQCT	DBQ	24	MLA	330	16	6.5	9.0	2.1	8	16	Q1
CY74	FCT480BTQCT	DBQ	24	MLA	330	16	6.5	9.0	2.1	8	16	Q1
CY74F	CT480BTSOCT	DW	24	TAI	330	24	10.75	15.7	2.7	12	24	Q1



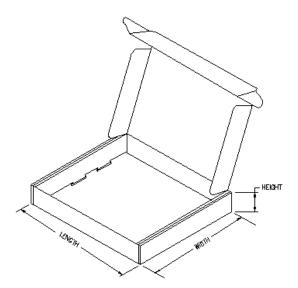
## TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CY74FCT480ATQCT	DBQ	24	MLA	0.0	0.0	0.0
CY74FCT480BTQCT	DBQ	24	MLA	0.0	0.0	0.0
CY74FCT480BTSOCT	DW	24	TAI	346.0	346.0	41.0





19-May-2007



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